# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

| | |
|---|---|
| **1.1 Company** | STMicroelectronics International N.V |
| **1.2 PCN No.** | EMBEDDED PROCESSING/25/15679 |
| **1.3 Title of PCN** | Bonding wires change to Copper on M24256E CMOS F9V |
| **1.4 Product Category** | M24256E CMOS F9V EEPROM product in TSSOP8 & DFN8 |
| **1.5 Issue date** | 2025-08-07 |

## 2. PCN Team

| | |
|---|---|
| **2.1 Contact supplier** | |
| **2.1.1 Name** | ROBERTSON HEATHER |
| **2.1.2 Phone** | +1 8475853058 |
| **2.1.3 Email** | heather.robertson@st.com |
| **2.2 Change responsibility** | |
| **2.2.1 Product Manager** | David RICHETTO |
| **2.1.2 Marketing Manager** | Sylvain FIDELIS |
| **2.1.3 Quality Manager** | Mickael DENAIS-ALLICHON |

## 3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|---|---|---|
| Materials | Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material) | N/A |

## 4. Description of change

| | Old | New |
|---|---|---|
| **4.1 Description** | The M24256E product processed with the CMOS F9V technology and assembled in TSSOP8 at ST Shenzhen (China) and in DFN8 at ST Calamba (Philippines) with Gold bonding wires... | ...will be now assembled with Copper bonding wires. |
| **4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?** | - Form: No change<br>- Fit: No change<br>- Function: No change | |

## 5. Reason / motivation for change

| | |
|---|---|
| **5.1 Motivation** | The strategy of STMicroelectronics CS Division is to support our customers on a long-term basis. In line with this commitment, the qualification of the M24256E EEPROM products in TSSOP8 and DFN8 using Copper bonding wires allows us to follow industry trend and long-term competitiveness and consequently improve the service to our customers. |
| **5.2 Customer Benefit** | CAPACITY INCREASE |

## 6. Marking of parts / traceability of change

| | |
|---|---|
| **6.1 Description** | N/A |

## 7. Timing / schedule

| | |
|---|---|
| **7.1 Date of qualification results** | 2025-08-14 |
| **7.2 Intended start of delivery** | 2025-10-27 |
| **7.3 Qualification sample available?** | Upon Request |

## 8. Qualification / Validation

| | | | |
|---|---|---|---|
| **8.1 Description** | | | |
| **8.2 Qualification report and qualification results** | In progress | **Issue Date** | |

## 9. Attachments (additional documentations)

15679 Public product.pdf
15679 PCN CS15679.pdf

## 10. Affected parts

| 10. 1 Current | | 10.2 New (if applicable) |
|---|---|---|
| **10.1.1 Customer Part No** | **10.1.2 Supplier Part No** | **10.1.2 Supplier Part No** |
| | M24256E-FDW6TP | |
| | M24256E-FMC6TG | |

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